



News Release / Presseinformation

Infineon Further Boosts GPS System Sensitivity Introducing the World's Smallest Fully Integrated Receive Front-End Module for GPS Applications with Low Current Consumption

Neubiberg, Germany – February 2, 2010 – Fulfilling requirements of the growing mobile GPS market for higher sensitivity, higher immunity against interference of cellular signals and low power consumption, Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) today introduced the next generation of its world's smallest GPS Receive Front-End Module. The new BGM781N11 further boosts GPS sensitivity to enable, for example, E911 emergency call requirements for mobile phones, personal navigation devices and other handheld systems, and GPS applications in vehicles. Including all key components to amplify a GPS signal and filter out interference, the module measures just 2.5mm x 2.5mm x 0.7mm in size, which is more than 60 percent smaller than the closest competitive product offering a similar integration level.

The BGM781N11 GPS receive front-end module integrates one GPS Low Noise Amplifier (LNA) and two Surface Acoustic Wave (SAW) filters with high electrostatic discharge (ESD) ruggedness in a tiny leadless TSNP11-2 package. With the BGM781N11 only two external passive components are required in a GPS application, compared to competitor solutions typically using between six and ten passives. As more and more features are added to new generations of high-end mobile phones, PCB space becomes the main limiting factor, so front-end modules that are small size and need few additional components are highly desirable. In addition, the BGM781N11 has very low power consumption, just 5.94 mW, and supports a wide power supply range between 1.5V and 3.6V.

In order to minimize damage from ESD in portable electronic products, the BGM781N11 offers a very high ESD robustness. With 8kV ESD Contact Discharge integrated at the RF input pin, manufacturers of GPS-enabled devices can easily achieve system ESD requirements (typically 8 kV) without additional ESD protection devices. Fulfilling the very important mobile GPS market requirement of higher sensi-

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Media Relations:
Worldwide Headquarters
U.S.A.
Asia
Japan
Investor Relations

Name:
Monika Sonntag
Mitch Ahiers
Chi Kang David Ong
Hirotaka Shiroguchi
EU/APAC/USA/CAN

Phone:
+49 89 234 24497
+1 408 503 2791
+65 6876 3070
+81 3 5745 7340
+49 89 234 26655

Email:
monika.sonntag@infineon.com
mitch.ahiers@infineon.com
david.ong@infineon.com
hirotaka.shiroguchi@infineon.com
investor.relations@infineon.com

tivity, Infineon's GPS receive front-end module offers a high gain of 18.6dB which is more than 20 percent better than the 16.5dB of current competitor solutions.

"Market experts expect GPS to further penetrate all kinds of applications and devices and to be featured in at least one third of all mobile phones to be produced in 2011, becoming a standard feature for the next generations of mobile phones," said Michael Mauer, Senior Marketing Director, RF and Protection Devices at Infineon Technologies. "Infineon is committed to continue developing a strong portfolio of completely integrated, high-performance GPS receive front-end modules. With the GPS receive front-end module BGM781N11 Infineon underlines our leading position in the GPS market."

Availability, Package and Pricing

The BGM781N11 GPS Receive Front-End Module is available in high-volume quantities. Infineon also provides evaluation kits. Pricing of the BGM781N11 starts at a 10,000-piece price of USD 1.00. It is shipped in a tiny leadless TSNP11-2 package of only 2.5mm x 2.5mm x 0.7mm in size.

Further technical information on the GPS Receive Front-End Module is available at www.infineon.com/BGM781N11

About Infineon

Infineon Technologies AG, Neubiberg, Germany, offers semiconductor and system solutions addressing three central challenges to modern society: energy efficiency, communications, and security. In the 2009 fiscal year (ending September), the company reported sales of Euro 3.03 billion with approximately 25,650 employees worldwide. With a global presence, Infineon operates through its subsidiaries in the U.S. from Milpitas, CA, in the Asia-Pacific region from Singapore, and in Japan from Tokyo. Infineon is listed on the Frankfurt Stock Exchange (ticker symbol: IFX) and in the USA on the over-the-counter market OTCQX International Premier (ticker symbol: IFNYY).

Further information is available at www.infineon.com

This news release is available online at www.infineon.com/press/

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Monika Sonntag
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Chi Kang David Ong
Hirotaka Shiroguchi
EU/APAC/USA/CAN

Phone:
+49 89 234 24497
+1 408 503 2791
+65 6876 3070
+81 3 5745 7340
+49 89 234 26655

Email:
monika.sonntag@infineon.com
mitch.ahiers@infineon.com
david.ong@infineon.com
hirotaka.shiroguchi@infineon.com
investor.relations@infineon.com